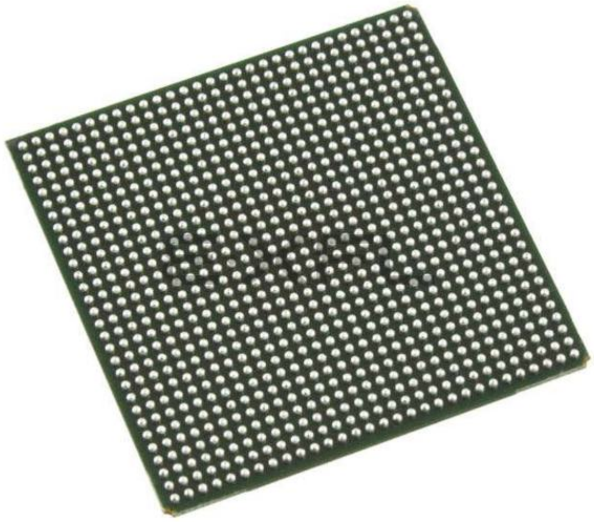

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

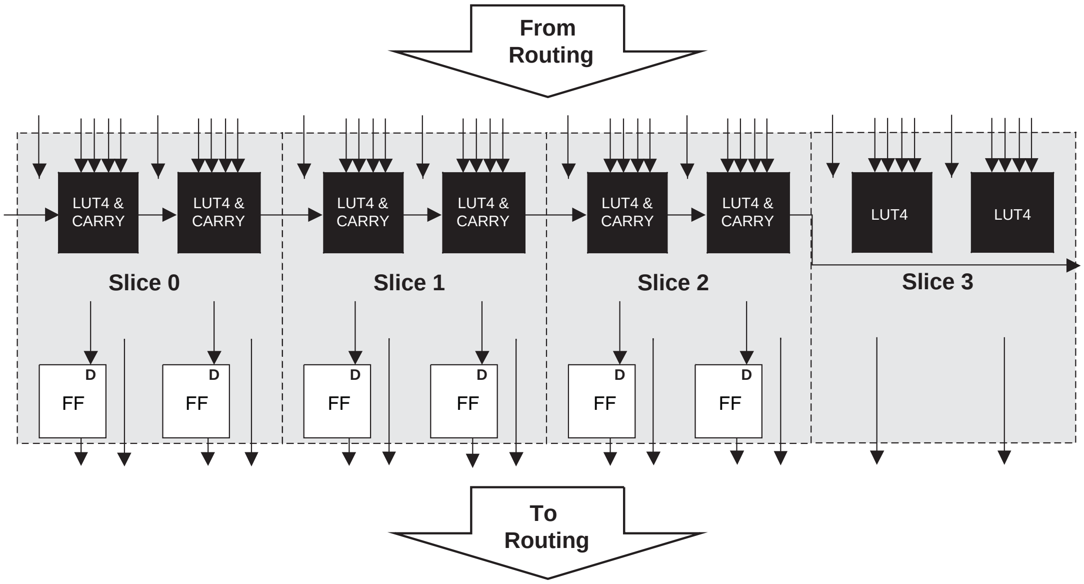
Details	
Product Status	Active
Number of LABs/CLBs	6000
Number of Logic Elements/Cells	48000
Total RAM Bits	4246528
Number of I/O	410
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m50e-5fn900c

PFU Blocks

The core of the LatticeECP2/M device consists of PFU blocks, which are provided in two forms, the PFU and PFF. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic and ROM functions. Except where necessary, the remainder of this data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-3. All the interconnections to and from PFU blocks are from routing. There are 50 inputs and 23 outputs associated with each PFU block.

Figure 2-3. PFU Diagram



Slice

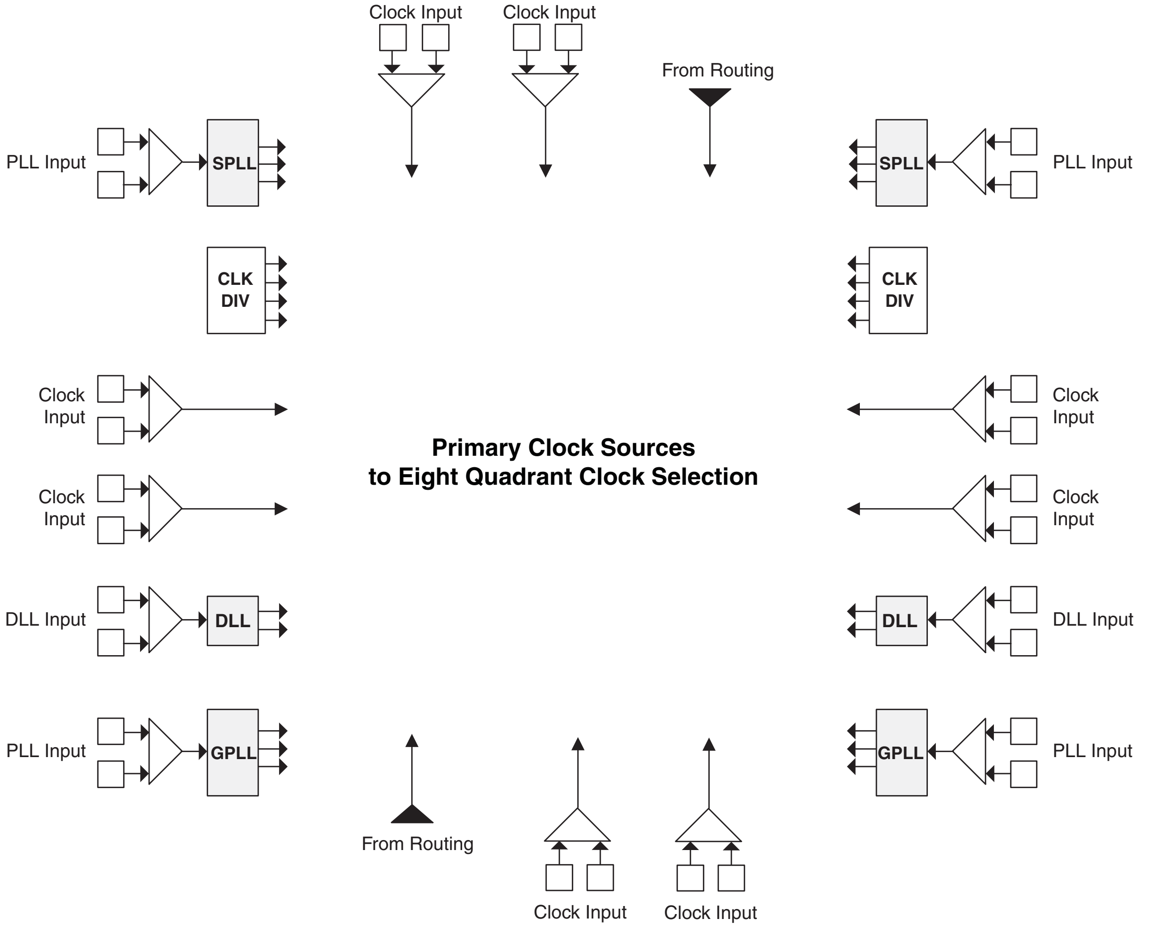
Slice 0 through Slice 2 contain two LUT4s feeding two registers, whereas Slice 3 contains two LUT4s only. For PFUs, Slice 0 and Slice 2 can also be configured as distributed memory, a capability not available in the PFF. Table 2-1 shows the capability of the slices in both PFF and PFU blocks along with the operation modes they enable. In addition, each PFU contains some logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-4 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge triggered or level sensitive clocks.

Table 2-1. Resources and Modes Available per Slice

	PFU BLock		PFF Block	
Slice	Resources	Modes	Resources	Modes
Slice 0	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 1	2 LUT4s and 2 Registers	Logic, Ripple, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 2	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 3	2 LUT4s	Logic, ROM	2 LUT4s	Logic, ROM

Slices 0, 1 and 2 have 14 input signals: 13 signals from routing and one from the carry-chain (from the adjacent slice or PFU). There are seven outputs: six to routing and one to carry-chain (to the adjacent PFU). Slice 3 has 13 input signals from routing and four signals to routing. Table 2-2 lists the signals associated with Slice 0 to Slice 2.

Figure 2-10. Primary Clock Sources for ECP2-50

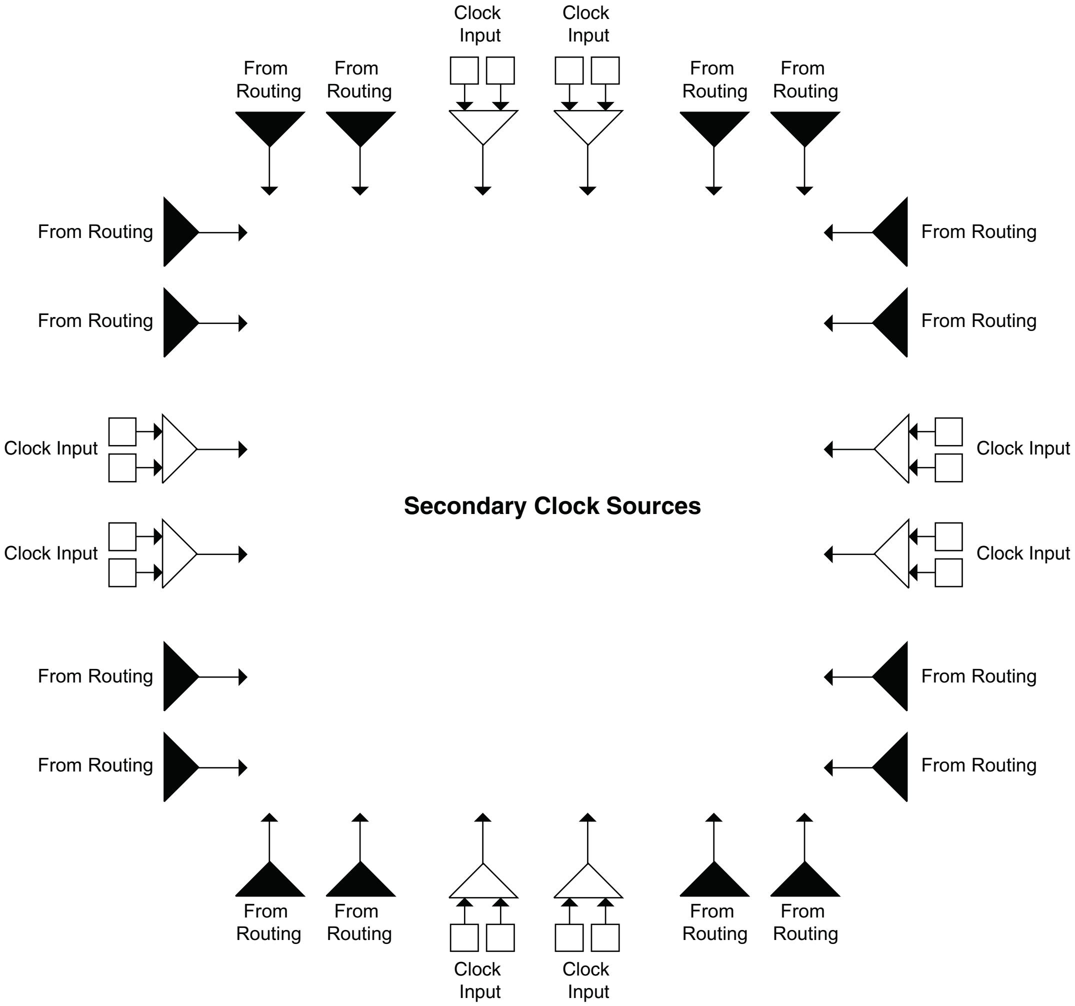


Note: This diagram shows sources for the ECP2-50 device. Smaller LatticeECP2 devices have fewer SPLLs. All LatticeECP2M devices have six SPLLs.

Secondary Clock/Control Sources

LatticeECP2/M devices derive secondary clocks (SC0 through SC7) from eight dedicated clock input pads and the rest from routing. Figure 2-11 shows the secondary clock sources.

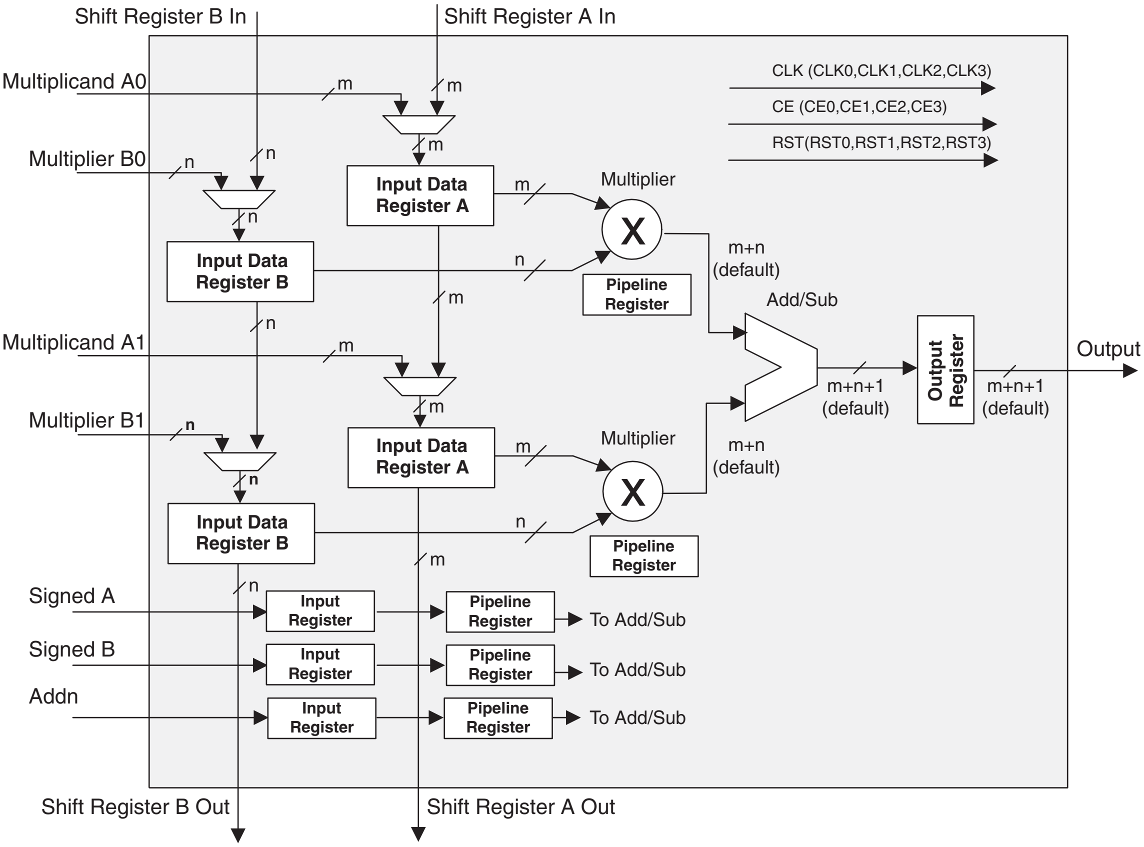
Figure 2-11. Secondary Clock Sources



MULTADDSUB sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and A2. The user can enable the input, output and pipeline registers. Figure 2-25 shows the MULTADDSUB sysDSP element.

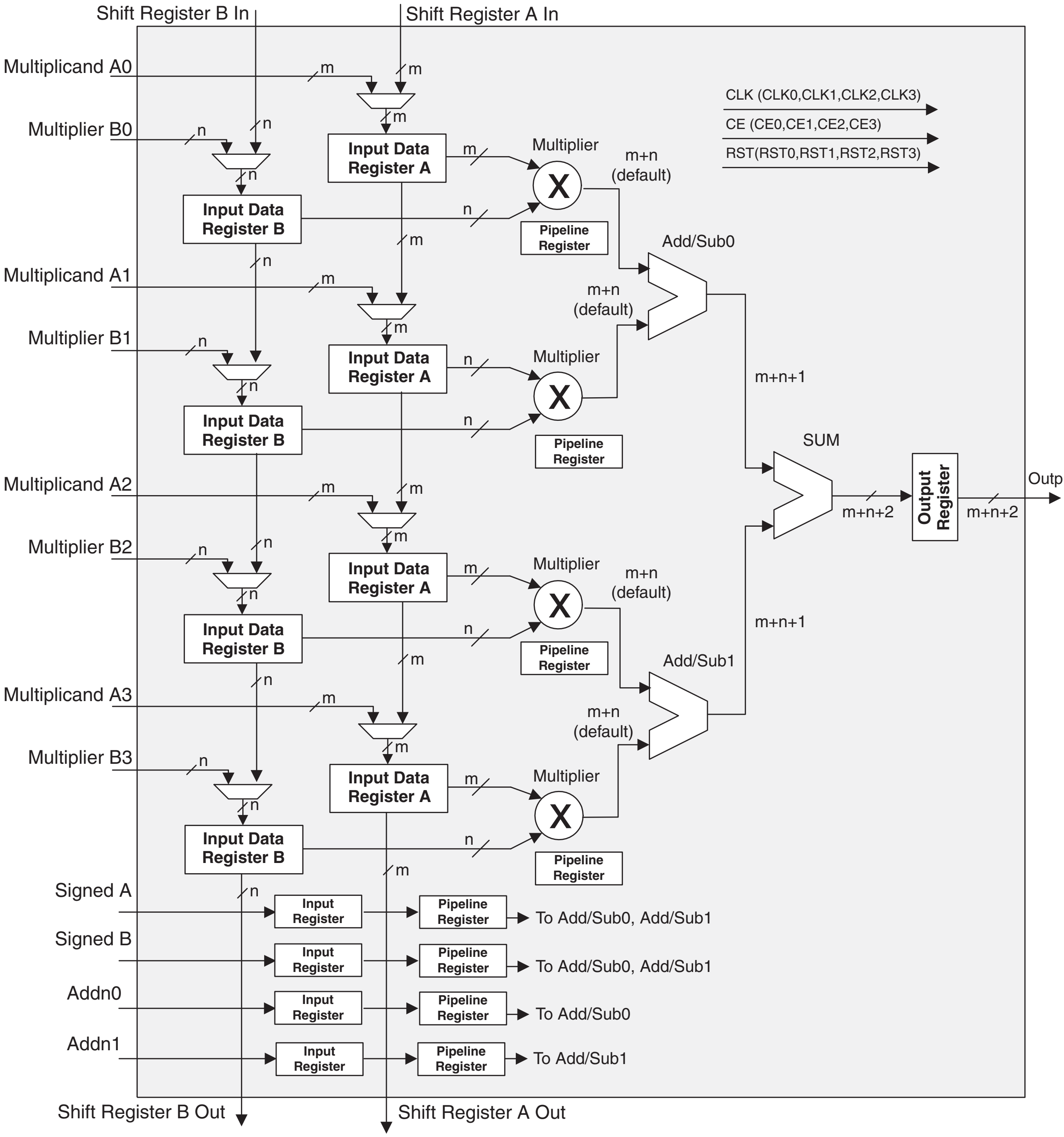
Figure 2-25. MULTADDSUB



MULTADDSUBSUM sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and B1. Additionally the operands A2 and B2 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A3 and B3. The result of both addition/subtraction are added in a summation block. The user can enable the input, output and pipeline registers. Figure 2-26 shows the MULTADDSUBSUM sysDSP element.

Figure 2-26. MULTADDSUBSUM



Clock, Clock Enable and Reset Resources

Global Clock, Clock Enable and Reset signals from routing are available to every DSP block. Four Clock, Reset and Clock Enable signals are selected for the sysDSP block. From four clock sources (CLK0, CLK1, CLK2, CLK3) sets of single-ended input buffers (both ratioed and referenced). One of the referenced input buffers can also be configured as a differential input.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

3. **Left and Right (Banks 2, 3, 6 and 7) sysI/O Buffer Pairs (50% Differential and 100% Single-Ended Outputs)**
   The sysI/O buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. One of the referenced input buffers can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

   LVDS differential output drivers are available on 50% of the buffer pairs on the left and right banks.

4. **Bank 8 sysI/O Buffer Pairs (Single-Ended Outputs, Only on Shared Pins When Not Used by Configuration)**
   The sysI/O buffers in Bank 8 consist of single-ended output drivers and single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

   The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

In LatticeECP2 devices, only the I/Os on the bottom banks have programmable PCI clamps. In LatticeECP2M devices, the I/Os on the left and bottom banks have programmable PCI clamps.

Typical sysI/O I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC}, V_{CCIO8} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user’s responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. For more information about controlling the output logic state with valid input logic levels during power-up in LatticeECP2/M devices, see the list of additional technical documentation at the end of this data sheet.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered-up before or together with the V_{CC} and V_{CCAUX} supplies.

Prior to and throughout programming of the FPGA, the I/O of the device have a weak-pullup resistor to V_{CCIO} on the input buffer and the output buffer is tri-stated. A pullup to V_{CCIO} is present on the input until the user programs the input differently in the FPGA design. See the DC Electrical Characteristics table of this data sheet. The pullup value will be between 20-30K ohms based on the V_{CCIO} voltage supplied on the board. This pullup will also remain active if the design does not use a particular I/O.

Supported sysI/O Standards

The LatticeECP2/M sysI/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 1.2V, 1.5V, 1.8V, 2.5V and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individual configuration options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, MLVDS, BLVDS, LVPECL, RSDS, differential SSTL and differential HSTL. Tables 2-13 and 2-14 show the I/

O standards (together with their supply and reference voltages) supported by LatticeECP2/M devices. For further information about utilizing the sysI/O buffer to support a variety of standards please see the the list of additional technical information at the end of this data sheet.

Table 2-13. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVCMOS33	—	—
LVCMOS25	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12	—	—
PCI 33	—	3.3
HSTL18 Class I, II	0.9	—
HSTL15 Class I	0.75	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I, II	0.9	—
Differential Interfaces		
Differential SSTL18 Class I, II	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I	—	—
Differential HSTL18 Class I, II	—	—
LVDS, MLVDS, LVPECL, BLVDS, RSDS	—	—

1 When not specified, V_{CCIO} can be set anywhere in the valid operating range (page 3-1).

SERDES Power Supply Requirements (LatticeECP2M Family Only)[1]

Over Recommended Operating Conditions

Symbol	Description	Typ.[2]	Units
Standby (Power Down)			
$I_{CCTX-SB}$	V_{CCTX} current (per channel)	10	µA
$I_{CCRX-SB}$	V_{CCRX} current (per channel)	75	µA
$I_{CCIB-SB}$	Input buffer current (per channel)	0	µA
$I_{CCOB-SB}$	Output buffer current (per channel)	0	µA
I_{CCP-SB}	SERDES PLL current (per quad)	30	µA
$I_{CCAX33-SB}$	SERDES termination current (per quad)	10	µA
Operating (Data Rate = 3.125 Gbps)			
$I_{CCTX-OP}$	V_{CCTX} current (per channel)	19	mA
$I_{CCRX-OP}$	V_{CCRX} current (per channel)	34	mA
$I_{CCIB-OP}$	Input buffer current (per channel)	4	mA
$I_{CCOB-OP}$	Output buffer current (per channel)	13	mA
I_{CCP-OP}	SERDES PLL current (per quad)	26	mA
$I_{CCAX33-OP}$	SERDES termination current (per quad)	0.01	mA

1. Equalization enabled, pre-emphasis disabled.
2. T_J = 25°C, power supplies at nominal voltage.

SERDES Power (LatticeECP2M Family Only)

Table 3-1 presents the SERDES power for one channel.

Table 3-1. SERDES Power[1]

Symbol	Description	Typ.[2]	Units
$P_{S-1CH-31}$	SERDES power (one channel @ 3.125 Gbps)	90	mW
$P_{S-1CH-25}$	SERDES power (one channel @ 2.5 Gbps)	87	mW
$P_{S-1CH-12}$	SERDES power (one channel @ 1.25 Gbps)	86	mW
$P_{S-1CH-02}$	SERDES power (one channel @ 250 Mbps)	76	mW

1. One quarter of the total quad power (includes contribution from common circuits, all channels in the quad operating, pre-emphasis disabled, equalization enabled).
2. Typical values measured at 25°C and 1.2V.

sysCLOCK GPLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)	Without external capacitor	20	—	420	MHz
		With external capacitor[5, 6]	2	—	420	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)	Without external capacitor	20	—	420	MHz
		With external capacitor[5]	5	—	50	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)	Without external capacitor	0.156	—	210	MHz
		With external capacitor[5]	0.039	—	25	MHz
f_{VCO}	PLL VCO Frequency		640	—	1280	MHz
f_{PFD}	Phase Detector Input Frequency	Without external capacitor	20	—	420	MHz
		With external capacitor[5, 6]	2	—	50	MHz
AC Characteristics						
t_{DT}	Output Clock Duty Cycle	Default duty cycle selected[3]	45	50	55	%
t_{PH}[4]	Output Phase Accuracy		—	—	±0.05	UI
t_{OPJIT}[1]	Output Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	—	±125	ps
		$50 \leq f_{OUT} < 100$ MHz	—		0.025	UIPP
		$f_{OUT} < 50$ MHz	—	—	0.04	UIPP
t_{SK}	Input Clock to Output Clock Skew	N/M = integer	—	—	±250	ps
t_W	Output Clock Pulse Width	At 90% or 10%	1	—	—	ns
t_{LOCK}[2]	PLL Lock-in Time	Without external capacitor	—	—	150	µs
		With external capacitor[5]	—	—	500	µs
t_{PA}	Programmable Delay Unit		85	130	360	ps
t_{IPJIT}	Input Clock Period Jitter		—	—	±200	ps
t_{FBKDLY}	External Feedback Delay		—	—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	—	ns
t_{RST}	RST Pulse Width (RESETM/RESETK)		15	—	—	ns
	Reset Signal Pulse Width (CNTRST)	Without external capacitor	500	—	—	ns
		With external capacitor[5]	20	—	—	µs

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock and no additional I/O pins toggling.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. Relative to CLKOP.
5. Value of external capacitor: 5.6 nF ±20%, NPO dielectric, ceramic chip capacitor, 1206 or smaller package, connected to PLLCAP pin.
6. f_{OUT} (max) = f_{IN} * 10 for f_{IN} < 5MHz.

PCI Express Electrical and Timing Characteristics

AC and DC Characteristics

Table 3-16. Transmit[1, 2]

Symbol	Description	Test Conditions	Min	Typ	Max	Units
UI	Unit interval		399.88	400	400.12	ps
$V_{TX\text{-}DIFF\_P\text{-}P}$	Differential peak-to-peak output voltage		0.8	1.0	1.2	V
$V_{TX\text{-}DE\text{-}RATIO}$	De-emphasis differential output voltage ratio		0	-3.5	-7.96	dB
$V_{TX\text{-}CM\text{-}AC\_P}$	RMS AC peak common-mode output voltage		—	20	—	mV
$V_{TX\text{-}CM\text{-}DC\text{-}LINE\text{-}DELTA}$	Maximum Common mode voltage delta between n and p channels		—	—	25	mV
$V_{TX\text{-}DC\text{-}CM}$	Tx DC common mode voltage		0	—	V_{CCOB} + 5%	V
$I_{TX\text{-}SHORT}$	Output short circuit current	$V_{TX\text{-}D+}$=0.0V $V_{TX\text{-}D-}$=0.0V	—	—	90	mA
$Z_{TX\text{-}DIFF\text{-}DC}$	Differential output impedance		80	100	120	Ohms
$T_{TX\text{-}RISE}$	Tx output rise time	20 to 80%	0.125	—	—	UI
$T_{TX\text{-}FALL}$	Tx output fall time	20 to 80%	0.125	—	—	UI
$L_{TX\text{-}SKEW}$	Lane-to-lane static output skew for all lanes in port/link		—	—	1.3	ns
$T_{TX\text{-}EYE}$	Transmitter eye width		0.75	—	—	UI
$T_{TX\text{-}EYE\text{-}MEDIAN\text{-}TO\text{-}MAX\text{-}JITTER}$[3]			—	—	0.125	UI
C_{TX}	AC coupling capacitor		75	—	200	nF

1. Values are measured at 2.5 Gbps.
2. Compliant to PCI Express v1.1.
3. Measured at 60ps with plug-in board and jitter due to socket removed.

Table 3-17. Receive

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
UI	Unit Interval		399.88	400	400.12	ps
$V_{RX\text{-}DIFF\_P\text{-}P}$	Differential peak-to-peak input voltage		0.175	—	—	V
$V_{RX\text{-}IDLE\text{-}DET\text{-}DIFF\_P\text{-}P}$	Idle detect threshold voltage		65	—	175	mV
$Z_{RX\text{-}DIFF\text{-}DC}$	DC differential input impedance		80	100	120	Ohms
$Z_{RX\text{-}DC}$	DC input impedance		40	50	60	Ohms
$Z_{RX\text{-}HIGH\text{-}IMP\text{-}DC}$[1]	Power-down DC input impedance		200K	—	—	Ohms
$T_{RX\text{-}EYE}$	Receiver eye width		0.4	—	—	UI
$T_{RX\text{-}EYE\text{-}MEDIAN\text{-}TO\text{-}MAX\text{-}JITTER}$			—	—	0.3	UI

Notes:
1. Measured with external AC-coupling on the receiver
2. Values are measured at 2.5 Gbps

LatticeECP2/M sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Byte Data Flow				
t_{SUCBDI}	Byte D[0:7] Setup Time to CCLK	7	—	ns
t_{HCBDI}	Byte D[0:7] Hold Time to CCLK	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
t_{SUCS}	CSN[0:1] Setup Time to CCLK	7	—	ns
t_{HCS}	CSN[0:1] Hold Time to CCLK	1	—	ns
t_{SUWD}	Write Signal Setup Time to CCLK	7	—	ns
t_{HWD}	Write Signal Hold Time to CCLK	1	—	ns
t_{DCB}	CCLK to BUSY Delay Time	—	12	ns
t_{CORD}	CCLK to Out for Read Data	—	12	ns
sysCONFIG Byte Slave Clocking				
t_{BSCH}	Byte Slave CCLK Minimum High Pulse	6	—	ns
t_{BSCL}	Byte Slave CCLK Minimum Low Pulse	9	—	ns
t_{BSCYC}	Byte Slave CCLK Cycle Time	15	—	ns
sysCONFIG Serial (Bit) Data Flow				
t_{SUSCDI}	DI Setup Time to CCLK Slave Mode	7	—	ns
t_{HSCDI}	DI Hold Time to CCLK Slave Mode	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
sysCONFIG Serial Slave Clocking				
t_{SSCH}	Serial Slave CCLK Minimum High Pulse	6	—	ns
t_{SSCL}	Serial Slave CCLK Minimum Low Pulse	6	—	ns
sysCONFIG POR, Initialization and Wake-up				
t_{ICFG}	Minimum Vcc to INITN High	—	28	ms
t_{VMC}	Time from t_{ICFG} to Valid Master CCLK	—	2	us
t_{PRGMRJ}	PROGRAMN Pin Pulse Rejection	—	8	ns
t_{PRGM}	PROGRAMN Low Time to Start Configuration	25	—	ns
t_{DINIT}	PROGRAMN High to INITN High Delay[1]	—	1.5	ms
$t_{DPPINIT}$	Delay Time from PROGRAMN Low to INITN Low	—	37	ns
$t_{DPPDONE}$	Delay Time from PROGRAMN Low to DONE Low	—	37	ns
t_{IODISS}	User I/O Disable from PROGRAMN Low	—	35	ns
t_{IOENSS}	User I/O Enabled Time from CCLK Edge During Wake-up Sequence	—	25	ns
t_{MWC}	Additional Wake Master Clock Signals after DONE Pin High	120	—	cycles
sysCONFIG SPI Port[2]				
t_{CFGX}	INITN High to CCLK Low	—	1	µs
t_{CSSPI}	INITN High to CSSPIN Low	—	2	us
t_{CSCCLK}	CCLK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CCLK Low to Output Valid	—	15	ns
t_{SOE}	CSSPIN[0:1] Active Setup Time	300	—	ns
t_{CSPID}	CSSPIN[0:1] Low to First CCLK Edge Setup Time	300+3cyc	600+6cyc	ns

PICs and DDR Data (DQ) Pins Associated with the DDR Strobe (DQS) Pin

PICs Associated with DQS Strobe	PIO Within PIC	DDR Strobe (DQS) and Data (DQ) Pins
For Left and Right Edges of the Device		
P[Edge] [n-4]	A	DQ
	B	DQ
P[Edge] [n-3]	A	DQ
	B	DQ
P[Edge] [n-2]	A	DQ
	B	DQ
P[Edge] [n-1]	A	DQ
	B	DQ
P[Edge] [n]	A	[Edge]DQSn
	B	DQ
P[Edge] [n+1]	A	DQ
	B	DQ
P[Edge] [n+2]	A	DQ
	B	DQ
P[Edge] [n+3]	A	DQ
	B	DQ
For Bottom Edge of the Device		
P[Edge] [n-4]	A	DQ
	B	DQ
P[Edge] [n-3]	A	DQ
	B	DQ
P[Edge] [n-2]	A	DQ
	B	DQ
P[Edge] [n-1]	A	DQ
	B	DQ
P[Edge] [n]	A	[Edge]DQSn
	B	DQ
P[Edge] [n+1]	A	DQ
	B	DQ
P[Edge] [n+2]	A	DQ
	B	DQ
P[Edge] [n+3]	A	DQ
	B	DQ
P[Edge] [n+4]	A	DQ
	B	DQ

Notes:

1. “n” is a row PIC number.
2. The DDR interface is designed for memories that support one DQS strobe up to 15 bits of data for the left and right edges and up to 17 bits of data for the bottom edge. In some packages, all the potential DDR data (DQ) pins may not be available. PIC numbering definitions are provided in the “Signal Names” column of the Signal Descriptions table.

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
W5	PL38B	6	LDQ42	C (LVDS)*	PL52B	6	LDQ56	C (LVDS)*
AC1	PL39A	6	LDQ42	T	PL53A	6	LDQ56	T
AD1	PL39B	6	LDQ42	C	PL53B	6	LDQ56	C
VCCIO	VCCIO6	6			VCCIO6	6		
Y6	PL40A	6	LDQ42	T (LVDS)*	PL54A	6	LDQ56	T (LVDS)*
Y5	PL40B	6	LDQ42	C (LVDS)*	PL54B	6	LDQ56	C (LVDS)*
AE2	PL41A	6	LDQ42	T	PL55A	6	LDQ56	T
AD2	PL41B	6	LDQ42	C	PL55B	6	LDQ56	C
GND	GNDIO6	-			GNDIO6	-		
AB3	PL42A	6	LDQS42	T (LVDS)*	PL56A	6	LDQS56	T (LVDS)*
AB2	PL42B	6	LDQ42	C (LVDS)*	PL56B	6	LDQ56	C (LVDS)*
W7	PL43A	6	LDQ42	T	PL57A	6	LDQ56	T
VCCIO	VCCIO6	6			VCCIO6	6		
W8	PL43B	6	LDQ42	C	PL57B	6	LDQ56	C
Y7	PL44A	6	LDQ42	T (LVDS)*	PL58A	6	LDQ56	T (LVDS)*
Y8	PL44B	6	LDQ42	C (LVDS)*	PL58B	6	LDQ56	C (LVDS)*
AC2	PL45A	6	LDQ42	T	PL59A	6	LDQ56	T
GND	GNDIO6	-			GNDIO6	-		
AD3	PL45B	6	LDQ42	C	PL59B	6	LDQ56	C
AC3	TCK	-			TCK	-		
AA8	TDI	-			TDI	-		
AB4	TMS	-			TMS	-		
AA5	TDO	-			TDO	-		
AB5	VCCJ	-			VCCJ	-		
AE3	PB2A	5	VREF2_5/BDQ6	T	PB2A	5	VREF2_5/BDQ6	T
AF3	PB2B	5	VREF1_5/BDQ6	C	PB2B	5	VREF1_5/BDQ6	C
AC4	PB3A	5	BDQ6	T	PB3A	5	BDQ6	T
AD4	PB3B	5	BDQ6	C	PB3B	5	BDQ6	C
AE4	PB4A	5	BDQ6	T	PB4A	5	BDQ6	T
AF4	PB4B	5	BDQ6	C	PB4B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
V9	PB5A	5	BDQ6	T	PB5A	5	BDQ6	T
W9	PB5B	5	BDQ6	C	PB5B	5	BDQ6	C
GND	GNDIO5	-			GNDIO5	-		
AA6	PB6A	5	BDQS6	T	PB6A	5	BDQS6	T
AB6	PB6B	5	BDQ6	C	PB6B	5	BDQ6	C
AC5	PB7A	5	BDQ6	T	PB7A	5	BDQ6	T
AD5	PB7B	5	BDQ6	C	PB7B	5	BDQ6	C
AA7	PB8A	5	BDQ6	T	PB8A	5	BDQ6	T
AB7	PB8B	5	BDQ6	C	PB8B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
AE5	PB9A	5	BDQ6	T	PB9A	5	BDQ6	T
AF5	PB9B	5	BDQ6	C	PB9B	5	BDQ6	C
AC7	PB10A	5	BDQ6	T	PB10A	5	BDQ6	T
AD7	PB10B	5	BDQ6	C	PB10B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

	LFE2-20E/20SE				LFE2-35E/35SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
U24	PR30B	3	RLM0_GPLLC_IN_A**/RDQ34	C (LVDS)*	PR44B	3	RLM0_GPLLC_IN_A**/RDQ48	C (LVDS)*
U25	PR30A	3	RLM0_GPLLT_IN_A**/RDQ34	T (LVDS)*	PR44A	3	RLM0_GPLLT_IN_A**/RDQ48	T (LVDS)*
R20	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
P18	VCC	3			VCCPLL	3		
T19	PR28B	3	RLM0_GDLLC_FB_A/RDQ25	C	PR42B	3	RLM0_GDLLC_FB_A/RDQ39	C
U20	PR28A	3	RLM0_GDLLT_FB_A/RDQ25	T	PR42A	3	RLM0_GDLLT_FB_A/RDQ39	T
GND	GNDIO3	-			GNDIO3	-		
T25	PR27B	3	RLM0_GDLLC_IN_A**/RDQ25	C (LVDS)*	PR41B	3	RLM0_GDLLC_IN_A**/RDQ39	C (LVDS)*
T26	PR27A	3	RLM0_GDLLT_IN_A**/RDQ25	T (LVDS)*	PR41A	3	RLM0_GDLLT_IN_A**/RDQ39	T (LVDS)*
T20	PR26B	3	RDQ25	C	PR40B	3	RDQ39	C
T22	PR26A	3	RDQ25	T	PR40A	3	RDQ39	T
VCCIO	VCCIO3	3			VCCIO3	3		
R26	PR25B	3	RDQ25	C (LVDS)*	PR39B	3	RDQ39	C (LVDS)*
R25	PR25A	3	RDQS25***	T (LVDS)*	PR39A	3	RDQS39***	T (LVDS)*
R22	NC	-			PR38B	3	RDQ39	C
GND	GNDIO3	-			GNDIO3	-		
T21	NC	-			PR38A	3	RDQ39	T
P26	NC	-			NC	-		
P25	NC	-			NC	-		
R24	NC	-			NC	-		
VCCIO	VCCIO3	3			VCCIO3	3		
R23	NC	-			NC	-		
P20	NC	-			NC	-		
R19	NC	-			NC	-		
P21	NC	-			PR34B	3	RDQ31	C
GND	GNDIO3	-			GNDIO3	-		
P19	NC	-			PR34A	3	RDQ31	T
P23	NC	-			PR33B	3	RDQ31	C (LVDS)*
P22	NC	-			PR33A	3	RDQ31	T (LVDS)*
N22	NC	-			PR32B	3	RDQ31	C
VCCIO	VCCIO3	3			VCCIO3	3		
R21	NC	-			PR32A	3	RDQ31	T
N26	NC	-			PR31B	3	RDQ31	C (LVDS)*
N25	NC	-			PR31A	3	RDQS31	T (LVDS)*
GND	GNDIO3	-			GNDIO3	-		
N19	PR24B	3	RDQ25	C	PR30B	3	RDQ31	C
N20	PR24A	3	RDQ25	T	PR30A	3	RDQ31	T
M26	PR23B	3	RDQ25	C (LVDS)*	PR29B	3	RDQ31	C (LVDS)*
M25	PR23A	3	RDQ25	T (LVDS)*	PR29A	3	RDQ31	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO3	3		
N18	PR22B	3	VREF2_3/RDQ25	C	PR28B	3	VREF2_3/RDQ31	C
N21	PR22A	3	VREF1_3/RDQ25	T	PR28A	3	VREF1_3/RDQ31	T
L26	PR21B	3	PCLKC3_0/RDQ25	C (LVDS)*	PR27B	3	PCLKC3_0/RDQ31	C (LVDS)*
L25	PR21A	3	PCLKT3_0/RDQ25	T (LVDS)*	PR27A	3	PCLKT3_0/RDQ31	T (LVDS)*
N24	PR19B	2	PCLKC2_0/RDQ16	C	PR25B	2	PCLKC2_0/RDQ22	C
M23	PR19A	2	PCLKT2_0/RDQ16	T	PR25A	2	PCLKT2_0/RDQ22	T

LFE2M-20E/SE and LFE2M-35E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
A7	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
C6	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
B4	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B3	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
A4	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
C3	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		
GNDIO	GNDIO1	-			GNDIO1	-		
VCCIO	VCCIO1	1			VCCIO1	1		
GNDIO	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
G10	VCCPLL	-			VCCPLL	-		
G7	VCC	-			VCC	-		
G9	VCC	-			VCC	-		
H7	VCC	-			VCC	-		
J10	VCC	-			VCC	-		
K10	VCC	-			VCC	-		
K8	VCC	-			VCC	-		
E7	VCCIO0	0			VCCIO0	0		
VCCIO	VCCIO0	0			VCCIO0	0		
E10	VCCIO1	1			VCCIO1	1		
VCCIO	VCCIO1	1			VCCIO1	1		
E14	VCCIO2	2			VCCIO2	2		
G12	VCCIO2	2			VCCIO2	2		
VCCIO	VCCIO2	2			VCCIO2	2		
K12	VCCIO3	3			VCCIO3	3		
M14	VCCIO3	3			VCCIO3	3		
VCCIO	VCCIO3	3			VCCIO3	3		
M10	VCCIO4	4			VCCIO4	4		
P12	VCCIO4	4			VCCIO4	4		
VCCIO	VCCIO4	4			VCCIO4	4		
M7	VCCIO5	5			VCCIO5	5		
P5	VCCIO5	5			VCCIO5	5		
VCCIO	VCCIO5	5			VCCIO5	5		
K5	VCCIO6	6			VCCIO6	6		
M3	VCCIO6	6			VCCIO6	6		
VCCIO	VCCIO6	6			VCCIO6	6		
E3	VCCIO7	7			VCCIO7	7		
G5	VCCIO7	7			VCCIO7	7		
VCCIO	VCCIO7	7			VCCIO7	7		
T15	VCCIO8	8			VCCIO8	8		
VCCIO	VCCIO8	8			VCCIO8	8		
G8	VCCAUX	-			VCCAUX	-		
H10	VCCAUX	-			VCCAUX	-		
J7	VCCAUX	-			VCCAUX	-		
K9	VCCAUX	-			VCCAUX	-		
A1	GND	-			GND	-		
A15	GND	-			GND	-		
A16	GND	-			GND	-		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AJ2	LLC_SQ_HDINN3	14		C
AH4	LLC_SQ_VCCTX3	14		
AK5	LLC_SQ_HDOUTP3	14		T
AK4	LLC_SQ_VCCOB3	14		
AJ5	LLC_SQ_HDOUTN3	14		C
AH5	LLC_SQ_VCCTX2	14		
AJ6	LLC_SQ_HDOUTN2	14		C
AH6	LLC_SQ_VCCOB2	14		
AK6	LLC_SQ_HDOUTP2	14		T
AH2	LLC_SQ_VCCRX2	14		
AJ3	LLC_SQ_HDINN2	14		C
AH3	LLC_SQ_VCCIB2	14		
AK3	LLC_SQ_HDINP2	14		T
AH7	LLC_SQ_VCCP	14		
AG7	LLC_SQ_REFCLKP	14		T
AF7	LLC_SQ_REFCLKN	14		C
AJ7	LLC_SQ_VCCAUX33	14		
AK11	LLC_SQ_HDINP1	14		T
AH11	LLC_SQ_VCCIB1	14		
AJ11	LLC_SQ_HDINN1	14		C
AH12	LLC_SQ_VCCRX1	14		
AK8	LLC_SQ_HDOUTP1	14		T
AH8	LLC_SQ_VCCOB1	14		
AJ8	LLC_SQ_HDOUTN1	14		C
AH9	LLC_SQ_VCCTX1	14		
AJ9	LLC_SQ_HDOUTN0	14		C
AK10	LLC_SQ_VCCOB0	14		
AK9	LLC_SQ_HDOUTP0	14		T
AH10	LLC_SQ_VCCTX0	14		
AJ12	LLC_SQ_HDINN0	14		C
AJ13	LLC_SQ_VCCIB0	14		
AK12	LLC_SQ_HDINP0	14		T
AH13	LLC_SQ_VCCRX0	14		
AF10	PB30A	5	BDQ33	T
AE8	PB30B	5	BDQ33	C
AE11	PB31A	5	BDQ33	T
VCCIO	VCCIO5	5		
AD9	PB31B	5	BDQ33	C
AE10	PB32A	5	BDQ33	T
AD10	PB32B	5	BDQ33	C
AE13	PB33A	5	BDQS33	T
GNDIO	GNDIO5	-		
AC12	PB33B	5	BDQ33	C

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AJ30	LRC_SQ_VCCIB0	13		
AK29	LRC_SQ_HDINP0	13		T
AH30	LRC_SQ_VCCRX0	13		
AG27	CFG2	8		
AD25	CFG1	8		
AG28	CFG0	8		
AG30	PROGRAMN	8		
AG29	CCLK	8		
AC24	INITN	8		
AF27	DONE	8		
GNDIO	GNDIO8	-		
AF28	WRITEN***	8		
AE26	CS1N***	8		
AB23	CSN***	8		
AF29	D0/SPIFASTN***	8		
VCCIO	VCCIO8	8		
AF30	D1***	8		
AD26	D2***	8		
AE29	D3***	8		
GNDIO	GNDIO8	-		
AE30	D4***	8		
AD29	D5***	8		
AC25	D6***	8		
AD30	D7/SPID0***	8		
VCCIO	VCCIO8	8		
AA22	DI/CSSPI0N***	8		
AC26	DOUT/CSON/CSSPI1N***	8		
AA23	BUSY/SISPI***	8		
AB22	RLM0_PLLCAP	3		
AC27	PR102B	3	RLM0_GDLLC_FB_A/RDQ99	C
GNDIO	GNDIO3	-		
AC28	PR102A	3	RLM0_GDLLT_FB_A/RDQ99	T
AC29	PR101B	3	RLM0_GDLLC_IN_A**/RDQ99	C (LVDS)*
AC30	PR101A	3	RLM0_GDLLT_IN_A**/RDQ99	T (LVDS)*
AB30	PR100B	3	RLM0_GPLLC_IN_A**/RDQ99	C
VCCIO	VCCIO3	3		
AA30	PR100A	3	RLM0_GPLLT_IN_A**/RDQ99	T
AB29	PR99B	3	RLM0_GPLLC_FB_A/RDQ99	C (LVDS)*
AB28	PR99A	3	RLM0_GPLLT_FB_A/RDQS99	T (LVDS)*
GNDIO	GNDIO3	-		
Y22	PR98B	3	RDQ99	C
Y23	PR98A	3	RDQ99	T
AB26	PR97B	3	RDQ99	C (LVDS)*

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE					LFE2M100E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO1	-			GNDIO1	-		
F19	PT59B	1		C	PT68B	1		C
D18	PT59A	1		T	PT68A	1		T
L18	NC	-			PT67B	1		C
K19	NC	-			PT67A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
A18	PT57B	1	VREF2_1	C	PT66B	1	VREF2_1	C
B18	PT57A	1	VREF1_1	T	PT66A	1	VREF1_1	T
G18	PT56B	1	PCLKC1_0	C	PT65B	1	PCLKC1_0	C
E18	PT56A	1	PCLKT1_0	T	PT65A	1	PCLKT1_0	T
F18	PT55B	0	PCLKC0_0	C	PT64B	0	PCLKC0_0	C
GNDIO	GNDIO0	-			GNDIO0	-		
G19	PT55A	0	PCLKT0_0	T	PT64A	0	PCLKT0_0	T
H18	PT54B	0	VREF2_0	C	PT63B	0	VREF2_0	C
K18	PT54A	0	VREF1_0	T	PT63A	0	VREF1_0	T
VCCIO	VCCIO0	0			VCCIO0	0		
J18	PT53B	0		C	PT60B	0		C
L17	PT53A	0		T	PT60A	0		T
G17	PT52B	0		C	PT59B	0		C
-	-	-			GNDIO0	-		
J17	PT52A	0		T	PT59A	0		T
H17	PT51B	0		C	PT58B	0		C
-	-	-			VCCIO0	0		
K17	PT51A	0		T	PT58A	0		T
B17	PT50B	0		C	PT57B	0		C
GNDIO	GNDIO0	-			-	-		
A17	PT50A	0		T	PT57A	0		T
D17	PT49B	0		C	PT56B	0		C
VCCIO	VCCIO0	0			-	-		
F17	PT49A	0		T	PT56A	0		T
B16	PT48B	0		C	PT55B	0		C
A16	PT48A	0		T	PT55A	0		T
-	-	-			GNDIO0	-		
-	-	-			VCCIO0	0		
E17	PT47B	0		C	PT52B	0		C
C17	PT47A	0		T	PT52A	0		T
K16	PT46B	0		C	PT51B	0		C
J15	PT46A	0		T	PT51A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
G16	PT45B	0		C	PT50B	0		C
H15	PT45A	0		T	PT50A	0		T
A15	PT44B	0		C	PT49B	0		C
B15	PT44A	0		T	PT49A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
L16	PT43B	0		C	PT48B	0		C
K15	PT43A	0		T	PT48A	0		T
F16	PT42B	0		C	PT47B	0		C
E16	PT42A	0		T	PT47A	0		T
E15	PT41B	0		C	PT46B	0		C

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

	LFE2M70E/SE				LFE2M100E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AE12	NC	-			NC	-		
AE13	NC	-			NC	-		
AE19	NC	-			NC	-		
AE21	NC	-			NC	-		
AE22	NC	-			NC	-		
AE23	NC	-			NC	-		
AF11	NC	-			NC	-		
AF21	NC	-			NC	-		
AF22	NC	-			NC	-		
AF24	NC	-			NC	-		
AF8	NC	-			NC	-		
AF9	NC	-			NC	-		
AG10	NC	-			NC	-		
AG11	NC	-			NC	-		
AG24	NC	-			NC	-		
AG25	NC	-			NC	-		
AG26	NC	-			NC	-		
AG3	NC	-			NC	-		
AG7	NC	-			NC	-		
AG8	NC	-			NC	-		
AG9	NC	-			NC	-		
AH10	NC	-			NC	-		
AH11	NC	-			NC	-		
AH13	NC	-			NC	-		
AH24	NC	-			NC	-		
AH25	NC	-			NC	-		
AH26	NC	-			NC	-		
AH27	NC	-			NC	-		
AH5	NC	-			NC	-		
AH6	NC	-			NC	-		
AH7	NC	-			NC	-		
AH8	NC	-			NC	-		
AH9	NC	-			NC	-		
AJ10	NC	-			NC	-		
AJ11	NC	-			NC	-		
AJ13	NC	-			NC	-		
AJ24	NC	-			NC	-		
AJ25	NC	-			NC	-		
AJ26	NC	-			NC	-		
AJ27	NC	-			NC	-		
AJ3	NC	-			NC	-		
AJ4	NC	-			NC	-		
AJ5	NC	-			NC	-		
AJ6	NC	-			NC	-		
AJ7	NC	-			NC	-		
AJ8	NC	-			NC	-		
AJ9	NC	-			NC	-		
AK10	NC	-			NC	-		
AK11	NC	-			NC	-		

LatticeECP2 S-Series Devices, Conventional Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6SE-5T144C	90	1.2V	-5	TQFP	144	Com	6
LFE2-6SE-6T144C	90	1.2V	-6	TQFP	144	Com	6
LFE2-6SE-7T144C	90	1.2V	-7	TQFP	144	Com	6
LFE2-6SE-5F256C	190	1.2V	-5	fpBGA	256	Com	6
LFE2-6SE-6F256C	190	1.2V	-6	fpBGA	256	Com	6
LFE2-6SE-7F256C	190	1.2V	-7	fpBGA	256	Com	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12SE-5T144C	93	1.2V	-5	TQFP	144	Com	12
LFE2-12SE-6T144C	93	1.2V	-6	TQFP	144	Com	12
LFE2-12SE-7T144C	93	1.2V	-7	TQFP	144	Com	12
LFE2-12SE-5Q208C	131	1.2V	-5	PQFP	208	Com	12
LFE2-12SE-6Q208C	131	1.2V	-6	PQFP	208	Com	12
LFE2-12SE-7Q208C	131	1.2V	-7	PQFP	208	Com	12
LFE2-12SE-5F256C	193	1.2V	-5	fpBGA	256	Com	12
LFE2-12SE-6F256C	193	1.2V	-6	fpBGA	256	Com	12
LFE2-12SE-7F256C	193	1.2V	-7	fpBGA	256	Com	12
LFE2-12SE-5F484C	297	1.2V	-5	fpBGA	484	Com	12
LFE2-12SE-6F484C	297	1.2V	-6	fpBGA	484	Com	12
LFE2-12SE-7F484C	297	1.2V	-7	fpBGA	484	Com	12

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-20SE-5Q208C	131	1.2V	-5	PQFP	208	Com	20
LFE2-20SE-6Q208C	131	1.2V	-6	PQFP	208	Com	20
LFE2-20SE-7Q208C	131	1.2V	-7	PQFP	208	Com	20
LFE2-20SE-5F256C	193	1.2V	-5	fpBGA	256	Com	20
LFE2-20SE-6F256C	193	1.2V	-6	fpBGA	256	Com	20
LFE2-20SE-7F256C	193	1.2V	-7	fpBGA	256	Com	20
LFE2-20SE-5F484C	331	1.2V	-5	fpBGA	484	Com	20
LFE2-20SE-6F484C	331	1.2V	-6	fpBGA	484	Com	20
LFE2-20SE-7F484C	331	1.2V	-7	fpBGA	484	Com	20
LFE2-20SE-5F672C	402	1.2V	-5	fpBGA	672	Com	20
LFE2-20SE-6F672C	402	1.2V	-6	fpBGA	672	Com	20
LFE2-20SE-7F672C	402	1.2V	-7	fpBGA	672	Com	20